# PRODUCT / PROCESS CHANGE NOTIFICATION

## 1. PCN basic data

| | |
|---|---|
| **1.1 Company** | STMicroelectronics International N.V |
| **1.2 PCN No.** | AMS/20/12142 |
| **1.3 Title of PCN** | Introduction of new Resin, new Bonding wire and new DAP Plating on DPAK package in Subcontractor Nantong Fujitsu (TFME) |
| **1.4 Product Category** | See product list |
| **1.5 Issue date** | 2020-08-11 |

## 2. PCN Team

| | |
|---|---|
| **2.1 Contact supplier** | |
| **2.1.1 Name** | KELLY MURPHY |
| **2.1.2 Phone** | |
| **2.1.3 Email** | kelly.murphy@st.com |
| **2.2 Change responsibility** | |
| **2.2.1 Product Manager** | Marcello SAN BIAGIO |
| **2.1.2 Marketing Manager** | Salvatore DI VINCENZO |
| **2.1.3 Quality Manager** | Giuseppe LISI |

## 3. Change

| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
|---|---|---|
| Materials | New direct material part number (same supplier, different supplier or new supplier), Bond wire material, diameter | Back end plant : Subcontractor Nantong Fujitsu (TFME China) |

## 4. Description of change

| | Old | New |
|---|---|---|
| **4.1 Description** | - Bonding wire : Gold 1.5 mil<br>- Molding compound : EME-500HA, Sumitomo<br>- Lead frame : TIN Plating Pure Sn with plating Ag die pad | - Bonding wire : CU 1.5 mil<br>- Molding Compound: EME-G700HF, Sumitomo<br>- Lead frame = TIN Plating Pure Sn with Bare Copper die pad and lock hole |
| **4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?** | No impact | |

## 5. Reason / motivation for change

| | |
|---|---|
| **5.1 Motivation** | This change will contribute to ST’s continuous service improvement and to improve the quality of the product, enhancing adhesion between lead frame surface & molding compound |
| **5.2 Customer Benefit** | QUALITY IMPROVEMENT |

## 6. Marking of parts / traceability of change

| | |
|---|---|
| **6.1 Description** | New finished good codes |

## 7. Timing / schedule

| | |
|---|---|
| **7.1 Date of qualification results** | 2020-04-30 |
| **7.2 Intended start of delivery** | 2020-10-10 |
| **7.3 Qualification sample available?** | Upon Request |

## 8. Qualification / Validation

| | | | |
|---|---|---|---|
| **8.1 Description** | 12142 12142_DPAK Cu wire.zip | | |
| **8.2 Qualification report and qualification results** | Available (see attachment) | **Issue Date** | 2020-08-11 |

## 9. Attachments (additional documentations)

12142 Public product.pdf
12142 12142_DPAK Cu wire.zip

## 10. Affected parts

| 10. 1 Current | | 10.2 New (if applicable) |
|---|---|---|
| **10.1.1 Customer Part No** | **10.1.2 Supplier Part No** | **10.1.2 Supplier Part No** |
| L78M05ABDT-TR | L78M05ABDT-TR | |
| L78M05CDT-TR | L78M05CDT-TR | |
| L78M09CDT-TR | L78M09CDT-TR | |
| L78M12CDT-TR | L78M12CDT-TR | |
| LD1117DT33CTR | LD1117DT33CTR | |
| LD1117DT33TR | LD1117DT33TR | |
| LD1117DT50TR | LD1117DT50TR | |
| LD1117DTTR | LD1117DTTR | |

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics – All rights reserved

# Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

***PCN Title :*** Introduction of new Resin, new Bonding wire and new DAP Plating on DPAK package in Subcontractor Nantong Fujitsu (TFME)
***PCN Reference :*** AMS/20/12142

***Subject :*** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

| | | |
|---|---|---|
| **L78M05CDT-TR** | **LD1117DTTR** | **LD1117DT50TR** |
| **L78M12CDT-TR** | **LD1117DT33CTR** | **L78M05ABDT-TR** |
| **LD1117DT33TR** | **L78M05ACDT-TR** | **L78M09CDT-TR** |

**IMPORTANT NOTICE – PLEASE READ CAREFULLY**

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics – All rights reserved